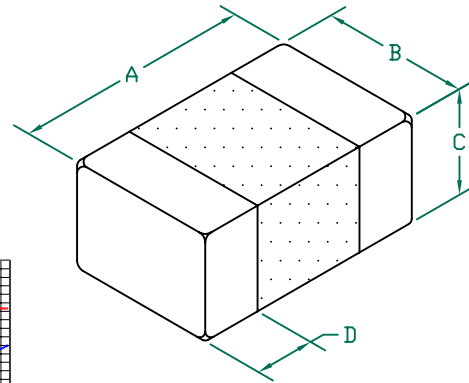


# HI0805Q310R-10

**UNCONTROLLED DOCUMENT**

**PHYSICAL DIMENSIONS:**

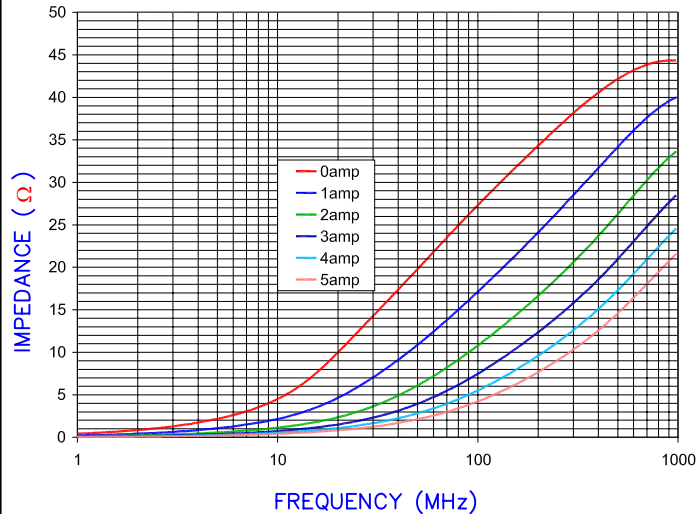
A	2.00 [.079]	+ 0.20 [.008]
B	1.25 [.049]	+ 0.20 [.008]
C	0.90 [.035]	+ 0.20 [.008]
D	0.51 [.020]	+ 0.25 [.010]



**ELECTRICAL CHARACTERISTICS:**

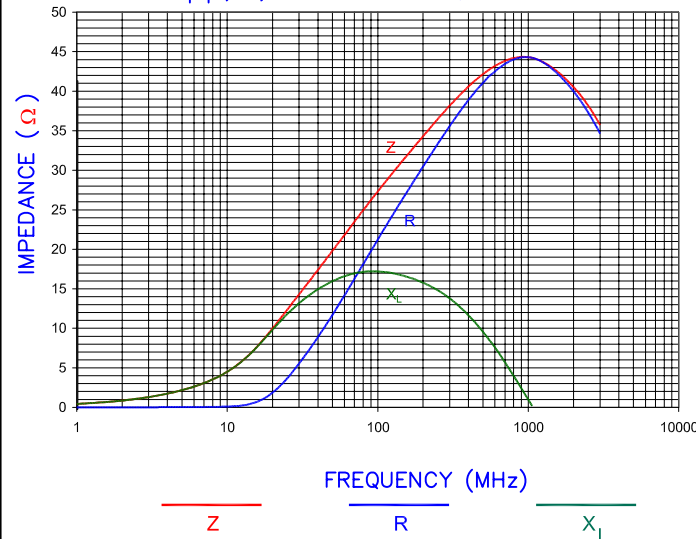
	Z @ 100MHz (Ω)	DCR (Ω)	Rated Current
Nominal	31		
Minimum	23		
Maximum	39	0.025	4500 mA

Z vs FREQUENCY  
IMPEDANCE UNDER DC BIAS



FREQUENCY (MHz)

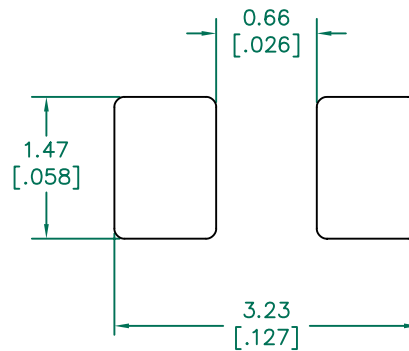
|Z|, R, AND X vs. FREQUENCY



FREQUENCY (MHz)

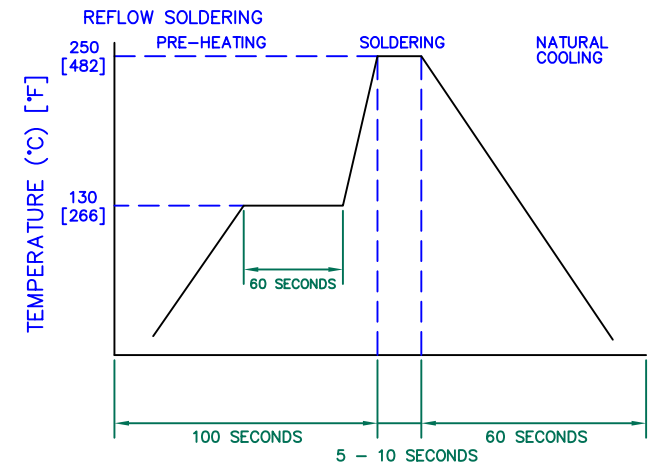


**LAND PATTERNS FOR REFLOW SOLDERING**



(For wave soldering, add 0.763 [.030] to this dimension.)

**RECOMMENDED SOLDERING CONDITIONS**



DIMENSIONS ARE IN mm [INCHES].				This print is the property of Laird Tech. and is loaned in confidence subject to return upon request and with the understanding that no copies shall be made without the written consent of Laird Tech. All rights to design or invention are reserved.			<b>Laird TECHNOLOGIES</b>	
				PROJECT/PART NUMBER:	REV	PART TYPE:	DRAWN BY:	
D	CHANGE TO PAPER TAPE	03/03/10	JUN	HI0805Q310R-10	D	CO-FIRE	TMB	
C	UPDATE COMPANY LOGO	06/05/09	JRK	DATE:	SCALE:	NTS	SHEET:	
B	UPDATE COMPANY LOGO ADD ROHS	01/16/08	JRK	04/01/04				
A	ORIGINAL DRAFT	04/01/04	TMB	GAD #	TOOL #		2 of 2	
REV	DESCRIPTION	DATE	INT	HI0805Q310R-10-D				